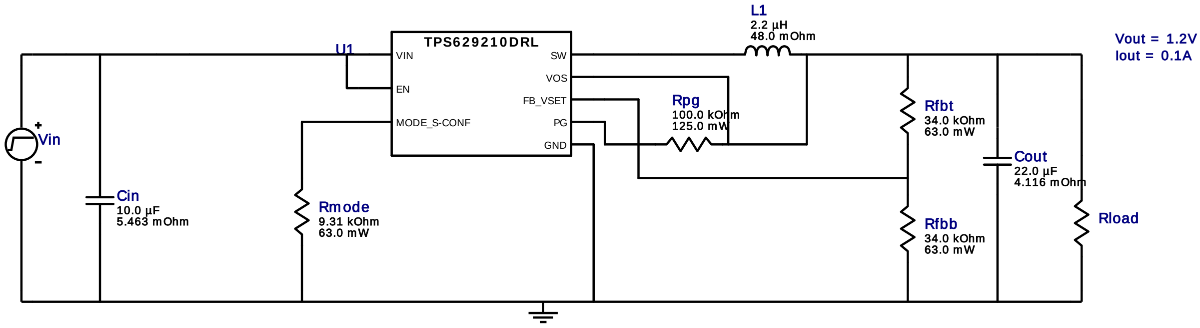
WEBENCH ® Design Report

VinMin = 5.5V
VinMax = 6.0V
Vout = 1.2V
Iout = 0.1A

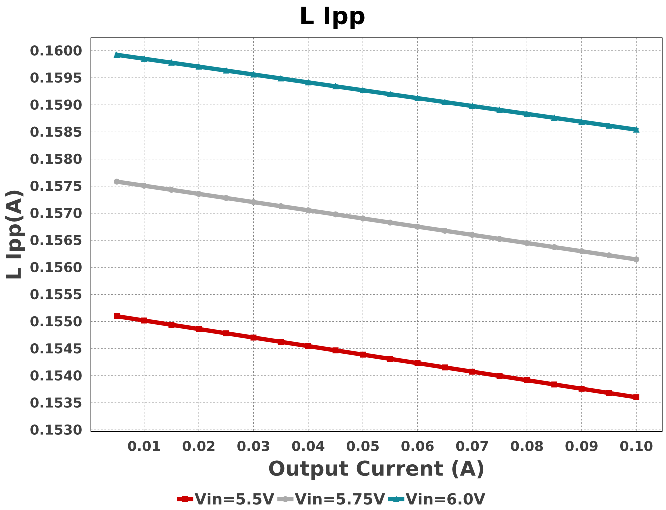
Device = TPS629210DRLR
Topology = Buck
Created = 2025-11-12 02:24:06.968
BOM Cost = $0.85
BOM Count = 8
Total Pd = 0.04W

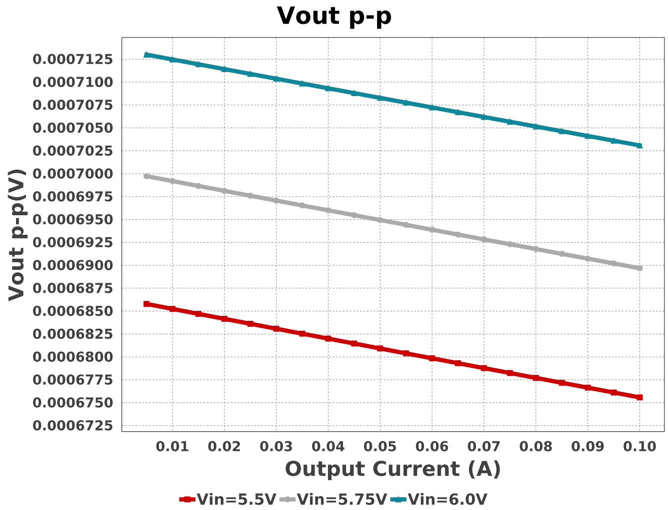
Design : 6 TPS629210DRLR
TPS629210DRLR 5.5V-6V to 1.20V @ 0.1A

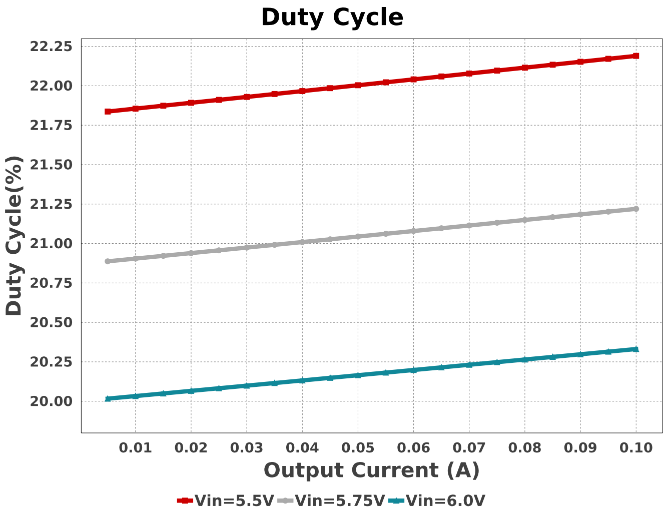


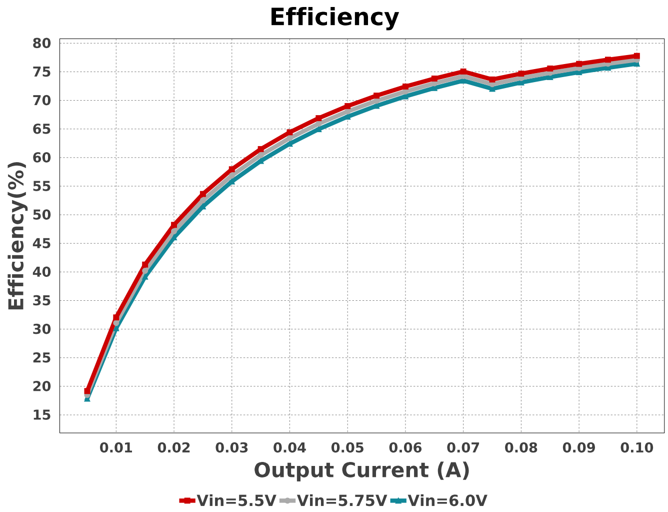
Electrical BOM

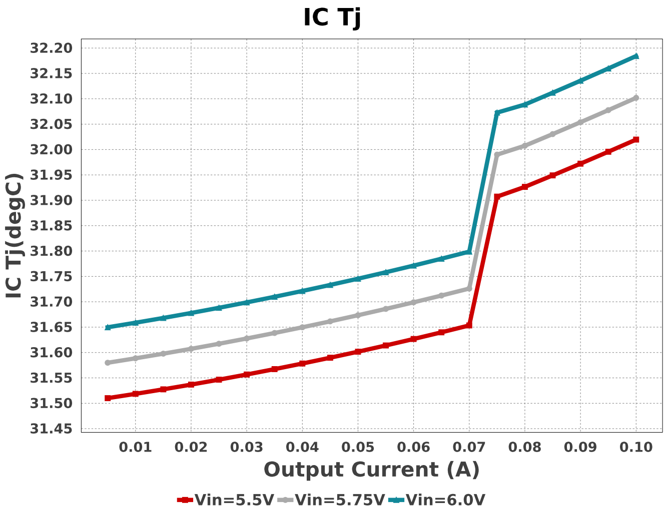
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cin	Taiyo Yuden	MSAST21GBB5106MTNA01 Series= X5R	Cap= 10.0 uF ESR= 5.463 mOhm VDC= 25.0 V IRMS= 2.36768 A	1	$0.04	0805 7 mm²
Cout	Taiyo Yuden	MCASA21GAB5226MTNA01 Series= X5R	Cap= 22.0 uF ESR= 4.116 mOhm VDC= 4.0 V IRMS= 3.70158 A	1	$0.06	0805 7 mm²
L1	Pulse Engineering	PA4332.222NLT	L= 2.2 µH 48.0 mOhm	1	$0.26	PA4332 27 mm²
Rfbb	Vishay-Dale	CRCW040234K0FKED Series= CRCW..e3	Res= 34.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm²
Rfbt	Vishay-Dale	CRCW040234K0FKED Series= CRCW..e3	Res= 34.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm²
Rmode	Vishay-Dale	CRCW04029K31FKED Series= CRCW..e3	Res= 9.31 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.01	0402 3 mm²
Rpg	Vishay-Dale	CRCW0805100KFKEA Series= CRCW..e3	Res= 100.0 kOhm Power= 125.0 mW Tolerance= 1.0%	1	$0.01	0805 7 mm²
U1	Texas Instruments	TPS629210DRLR	Switcher	1	$0.45	RGT0016C 16 mm²

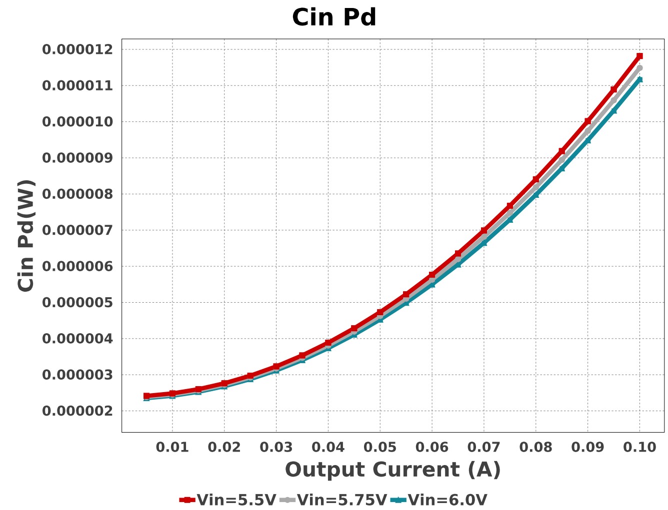

L Ipp
L Ipp(A)
0.1600
0.1595
0.1590
0.1585
0.1580
0.1575
0.1570
0.1565
0.1560
0.1555
0.1550
0.1545
0.1540
0.1535
0.1530
0.01 0.02 0.03 0.04 0.05 0.06 0.07 0.08 0.09 0.10
Output Current (A)
Vin=5.5V Vin=5.75V Vin=6.0V


Vout p-p
Vout p-p(V)
0.0007125
0.0007100
0.0007075
0.0007050
0.0007025
0.0007000
0.0006975
0.0006950
0.0006925
0.0006900
0.0006875
0.0006850
0.0006825
0.0006800
0.0006775
0.0006750
0.0006725
0.01 0.02 0.03 0.04 0.05 0.06 0.07 0.08 0.09 0.10
Output Current (A)
Vin=5.5V Vin=5.75V Vin=6.0V

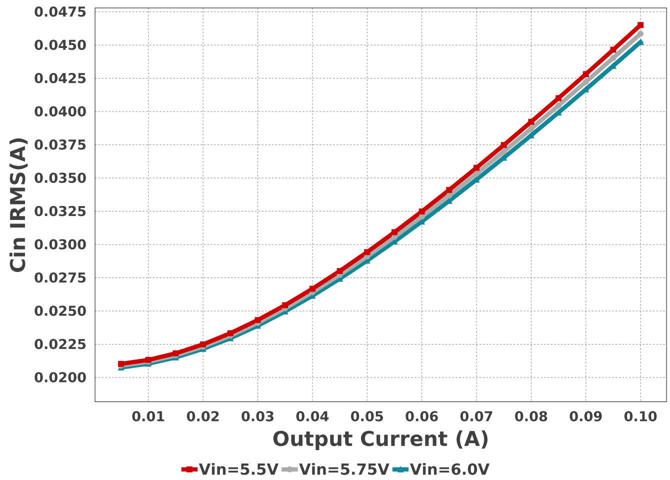

Duty Cycle
Duty Cycle(%)
22.25
22.00
21.75
21.50
21.25
21.00
20.75
20.50
20.25
20.00
0.01 0.02 0.03 0.04 0.05 0.06 0.07 0.08 0.09 0.10
Output Current (A)
Vin=5.5V Vin=5.75V Vin=6.0V


Efficiency
Efficiency(%)
80
75
70
65
60
55
50
45
40
35
30
25
20
15
0.01 0.02 0.03 0.04 0.05 0.06 0.07 0.08 0.09 0.10
Output Current (A)
Vin=5.5V Vin=5.75V Vin=6.0V

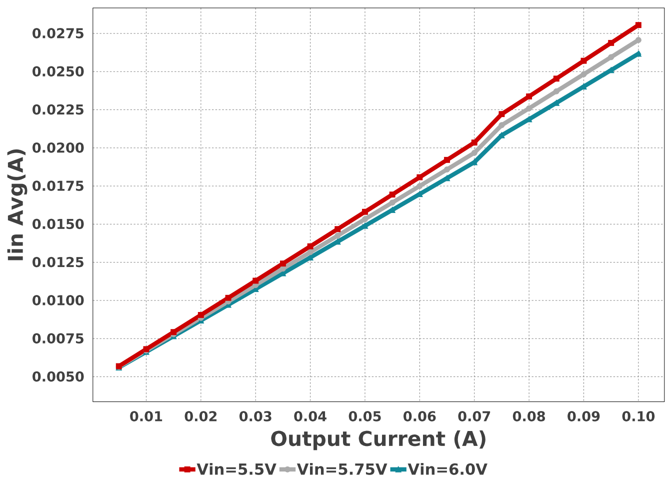

IC Tj
IC Tj(degC)
32.20
32.15
32.10
32.05
32.00
31.95
31.90
31.85
31.80
31.75
31.70
31.65
31.60
31.55
31.50
31.45
0.01 0.02 0.03 0.04 0.05 0.06 0.07 0.08 0.09 0.10
Output Current (A)
Vin=5.5V Vin=5.75V Vin=6.0V


Cin Pd
Cin Pd(W)
0.000012
0.000011
0.000010
0.000009
0.000008
0.000007
0.000006
0.000005
0.000004
0.000003
0.000002
0.01 0.02 0.03 0.04 0.05 0.06 0.07 0.08 0.09 0.10
Output Current (A)
Vin=5.5V Vin=5.75V Vin=6.0V

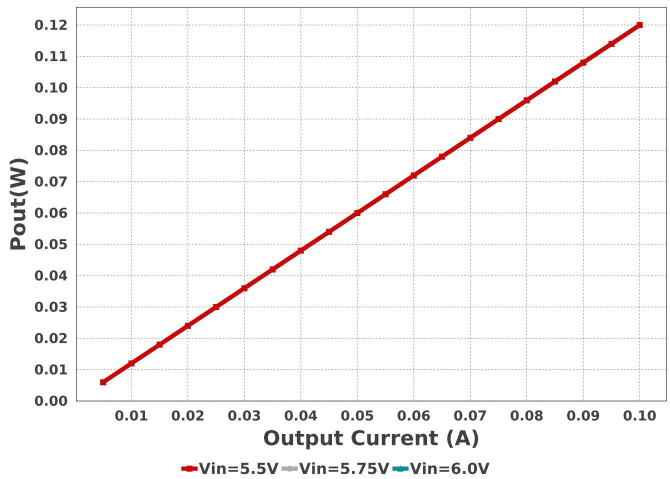
Cin IRMS



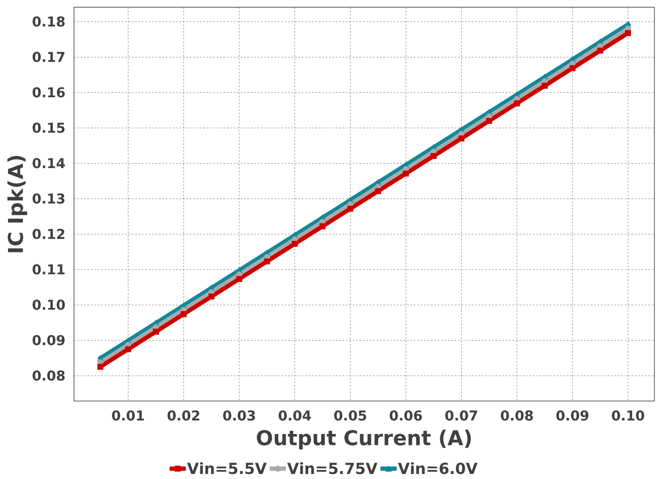
Iin Avg



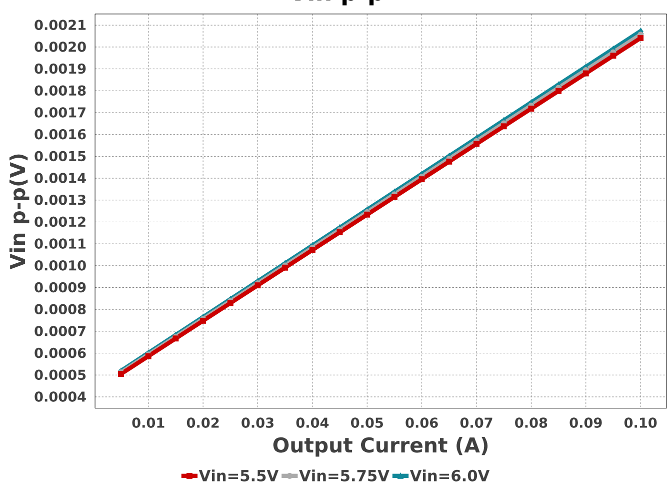
Pout



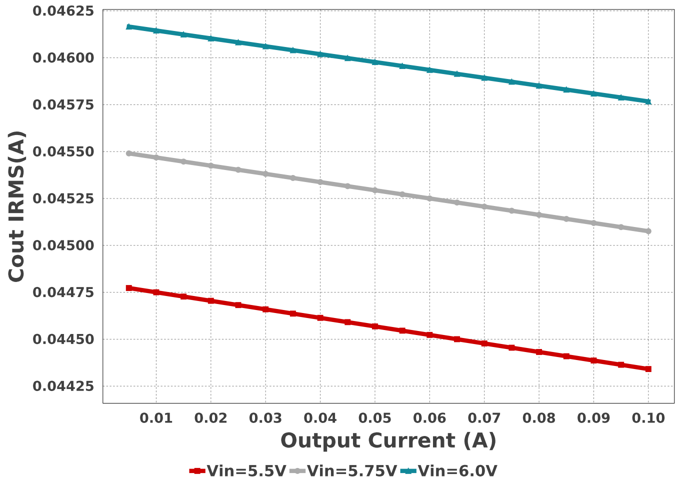
IC Ipk

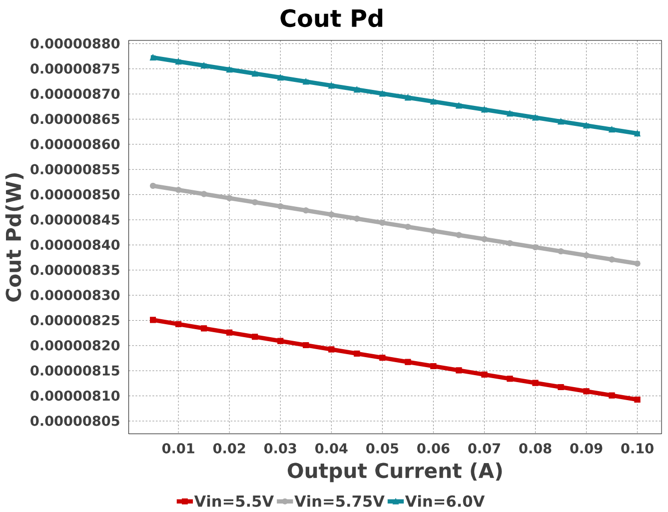


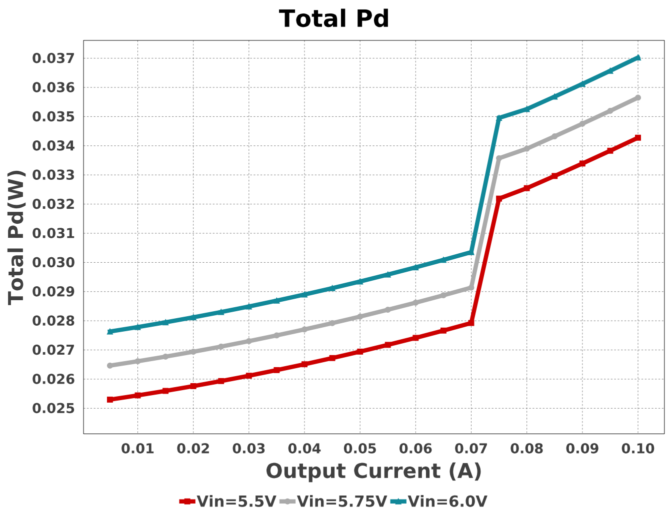
Vin p-p

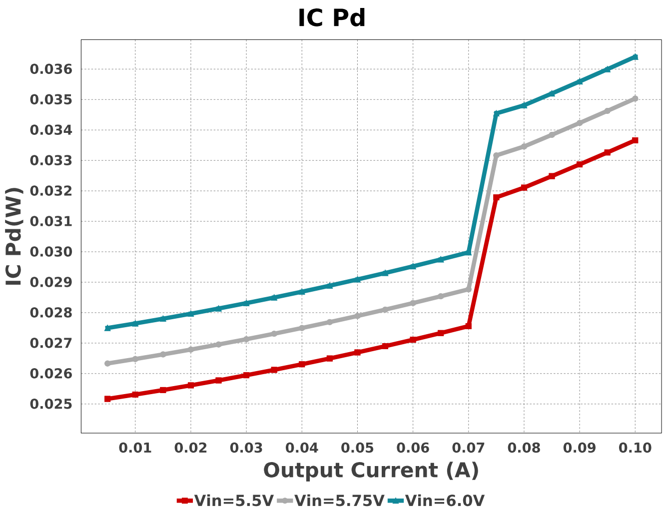


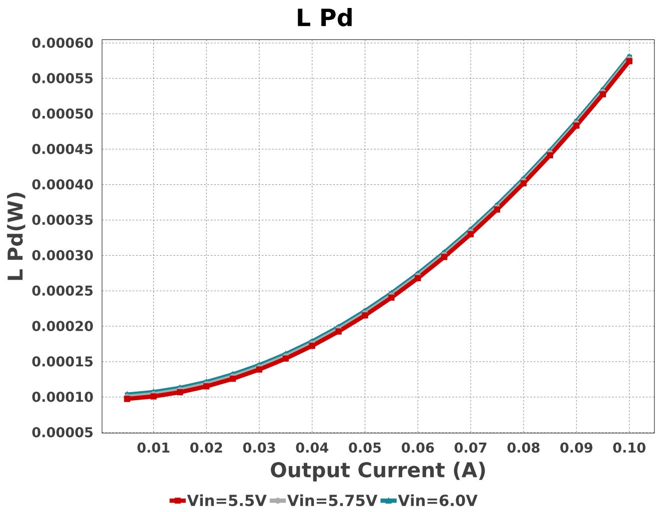
Cout IRMS











Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	45.229 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	11.175 µW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	45.767 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	8.622 µW	Capacitor	Output capacitor power dissipation
5.	IC Ipk	179.271 mA	IC	Peak switch current in IC
6.	IC Pd	36.404 mW	IC	IC power dissipation
7.	IC Tj	32.184 degC	IC	IC junction temperature
8.	ICThetaJA Effective	60.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
9.	Iin Avg	26.171 mA	IC	Average input current
10.	L Ipp	158.54 mA	Inductor	Peak-to-peak inductor ripple current
11.	L Pd	580.54 µW	Inductor	Inductor power dissipation
12.	Cin Pd	11.175 µW	Power	Input capacitor power dissipation
13.	Cout Pd	8.622 µW	Power	Output capacitor power dissipation
14.	IC Pd	36.404 mW	Power	IC power dissipation
15.	L Pd	580.54 µW	Power	Inductor power dissipation
16.	Total Pd	37.025 mW	Power	Total Power Dissipation
17.	BOM Count	8	System Information	Total Design BOM count
18.	Duty Cycle	20.331 %	System Information	Duty cycle
19.	Efficiency	76.421 %	System Information	Steady state efficiency
20.	FootPrint	72.0 mm²	System Information	Total Foot Print Area of BOM components
21.	Frequency	2.772 MHz	System Information	Switching frequency
22.	Iout	100.0 mA	System Information	Iout operating point
23.	Mode	CCM	System Information	Conduction Mode
24.	Pout	120.0 mW	System Information	Total output power

#	Name	Value	Category	Description
25.	Total BOM	$0.85	System Information	Total BOM Cost
26.	Vin	6.0 V	System Information	Vin operating point
27.	Vin p-p	2.073 mV	System Information	Peak-to-peak input voltage
28.	Vout	1.2 V	System Information	Operational Output Voltage
29.	Vout Actual	1.2 V	System Information	Vout Actual calculated based on selected voltage divider resistors
30.	Vout Tolerance	2.222 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
31.	Vout p-p	703.089 µV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	100.0 m	Maximum Output Current
VinMax	6.0	Maximum input voltage
VinMin	5.5	Minimum input voltage
Vout	1.2	Output Voltage
base_pn	TPS629210	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

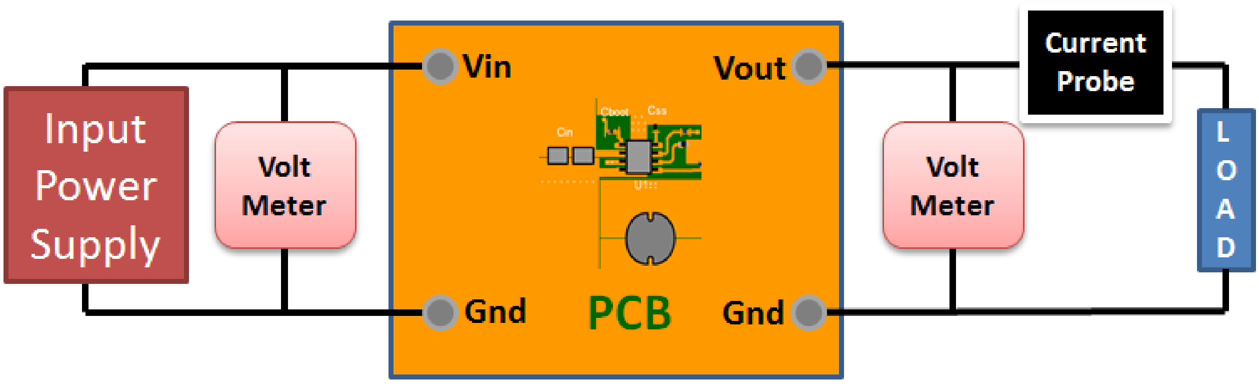
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 5.5V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.

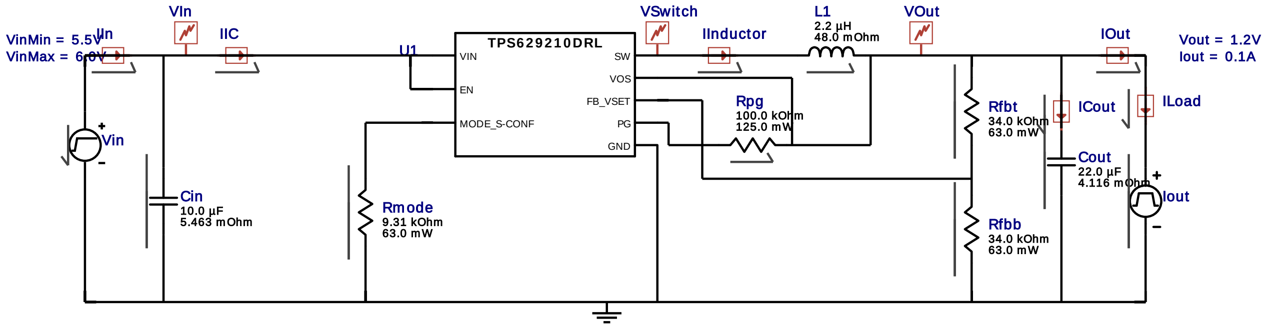


WEBENCH® Electrical Simulation Report

Design Id = 6

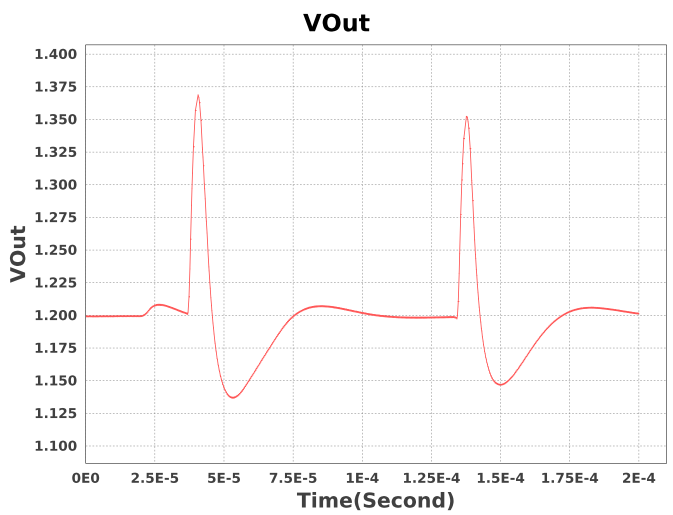
sim_id = 2

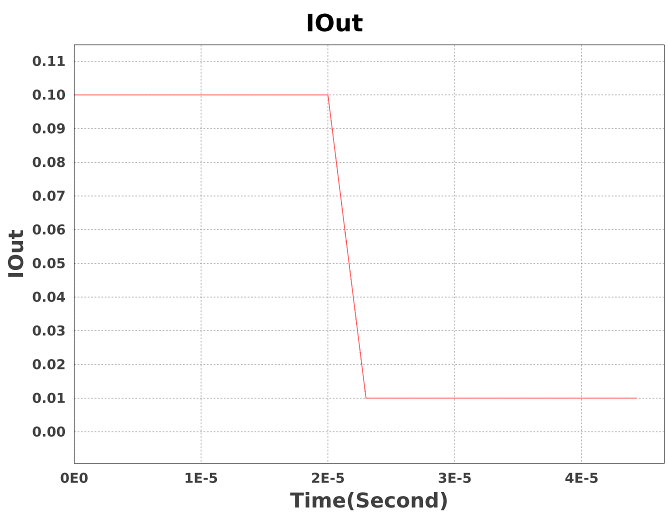
Simulation Type = Load Transient



Simulation Parameters

#	Name	Parameter Name	Description	Values
1.	ILoad	I	Load current	ILoad1 A
2.	Iout	signal_type	Signal Type	PULSE
		I1	Initial Current	0.1 A
		I2	Peak Current	0.01 A
		Td	Initial Time Delay	20u s
		Tf	Fall Time	3u s
		Tr	Rise Time	3u s
		Pw	Pulse Width	110u s





Design Assistance

1. Master key : 3090A28827CB0CC389CEC5F671D36AF3[v1]

2. **TPS629210** Product Folder : https://www.ti.com/product/TPS629210 : contains the data sheet and other resources.

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